









CEP840B

500V ▲ 0.66Ω ▲ 8.7A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type
N-channel enhancement mode
UL94V-0 rated flame retardant epoxy
TO220-3L package

Super high dense cell density for extremely low R_{DS(ON)} **High power and current handling capability**

MAXIMUM RATINGS

Parameter (T _c = 25°C, unless otherwise noted)		Characteristics
Drain-Source Voltage	V _{DS}	500V
Gate-Source Voltage	V _{GS}	±30V
Continuous Drain Current at T _C = 25°C	I _D	8.7A
Continuous Drain Current at T _C = 100°C	I _D	6.1A
Pulsed Drain Current Note 1	I _{DM} Note 5	34.8A
Maximum Power Dissipation at T _C = 25°C	P _D	150W
Power Dissipation Derating above 25°C	ΔP_D	1W/°C
Single Pulsed Avalanche Energy Note 6	E _{AS}	245mJ
Single Pulsed Avalanche Current Note 6	I _{AS}	7A
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +175°C

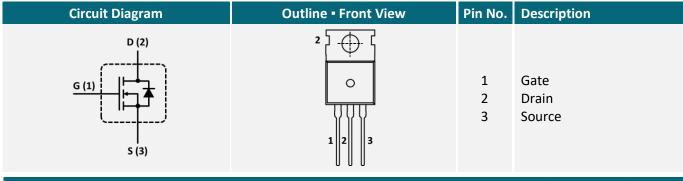
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R _{TH_JC}	1°C/W
Thermal Resistance, Junction-to-Ambient	R _{TH JA}	62.5°C/W

APPLICATIONS

General Lighting LED & CCFL	Industrial Inverters	Motors & Drives	Power Supplies	UPS

PIN DESCRIPTION



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ELECTRICAL CHARACTERISTICS ▲ T_C = 25°C, unless otherwise noted

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$	BV _{DSS}	500			V
Zero Gate Voltage Drain Current	$V_{DS} = 500V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	I_{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	I _{GSSR}			-100	nA
On Characteristics Note 2						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 4.3A$	R _{DS(ON)}		0.66	0.8	Ω
Dynamic Characteristics Note 3						
Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		955		pF
Output Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		140		pF
Reverse Transfer Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C_{RSS}		15		pF
Switching Characteristics Note 3						
Turn-On Delay Time	V_{DD} = 250V, V_{GS} = 10V, I_{D} = 4A, $R_{G(ext)}$ = 9.1 Ω	t _{D(ON)}		25		ns
Turn-On Rise Time	V_{DD} = 250V, V_{GS} = 10V, I_D = 4A, $R_{G(ext)}$ = 9.1 Ω	t_R		7		ns
Turn-Off Delay Time	V_{DD} = 250V, V_{GS} = 10V, I_D = 4A, $R_{G(ext)}$ = 9.1 Ω	t _{D(OFF)}		46		ns
Turn-Off Fall Time	V_{DD} = 250V, V_{GS} = 10V, I_D = 4A, $R_{G(ext)}$ = 9.1 Ω	t_{\scriptscriptstyleF}		8		ns
Total Gate Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_D = 7A$	Q_{G}		22		nC
Gate Source Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_{D} = 7A$	Q_{GS}		4		nC
Gate Drain Charge	$V_{DS} = 400V$, $V_{GS} = 10V$, $I_D = 7A$	Q_{GD}		9		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current		Is			8.7	Α
Drain-Source Diode Forward Voltage Note 2	$V_{GS} = 0V$, $I_S = 7A$	V_{SD}			1.5	V

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3: Guaranteed by design, not subject to production testing.
- 4: Limited only by maximum temperature allowed.
- 5: Pulse width limited by safe operating area.
- 6: L = 10mH, I_{AS} = 7A, V_{DD} = 60V, R_G = 25Ω, Starting T_J = 25°C



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE



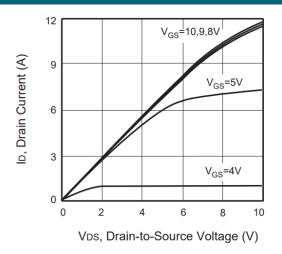


Fig. 2 • Transfer Characteristics

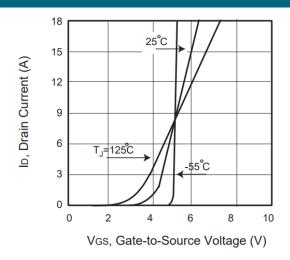


Fig. 3 • Capacitance

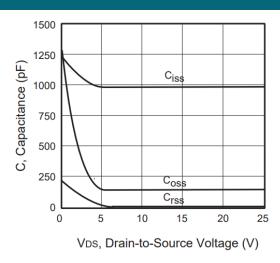


Fig. 4 • On-Resistance Variation with Temperature

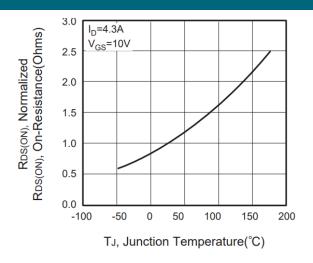


Fig. 5 • Gate Threshold Variation with Temperature

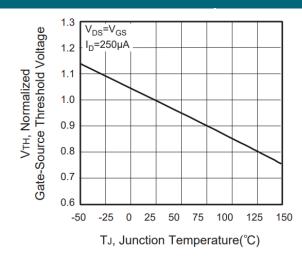
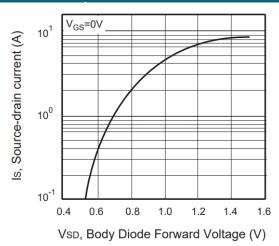


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



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Fig. 7 • Gate Charge

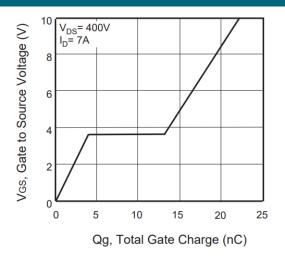


Fig. 8 • Maximum Safe Operating Area

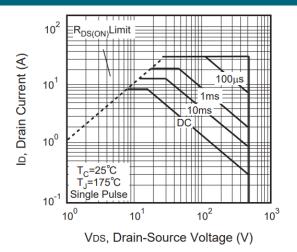
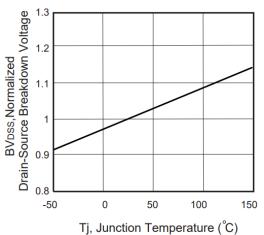


Fig. 9 • Breakdown Voltage Variation vs. Temperature





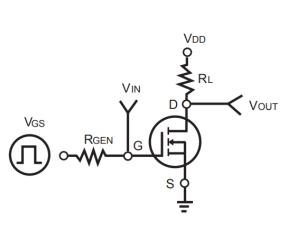
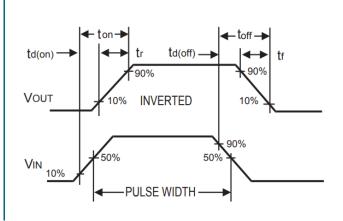


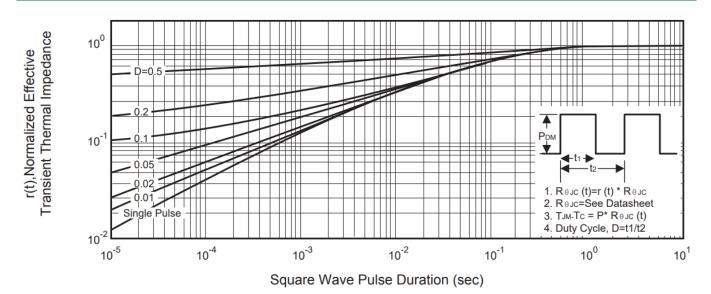
Fig. 11 • Switching Waveforms





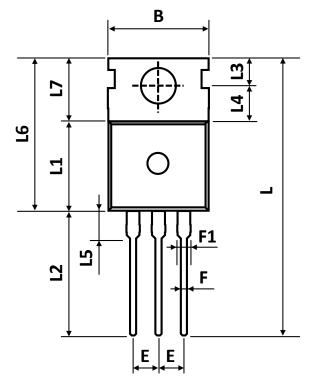
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

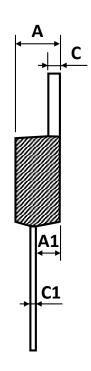
Fig. 12 • Normalized Thermal Transient Impedance Curve

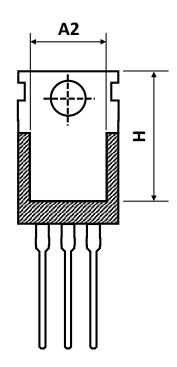




PACKAGE OUTLINE







Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
В	9.80	10.00	10.20
С	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
Н	12.95	13.25	13.55

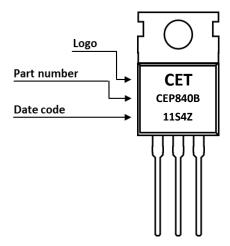
ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP840B	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs

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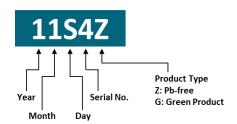


PART MARKING



DATE CODE

Example: 11S4Z



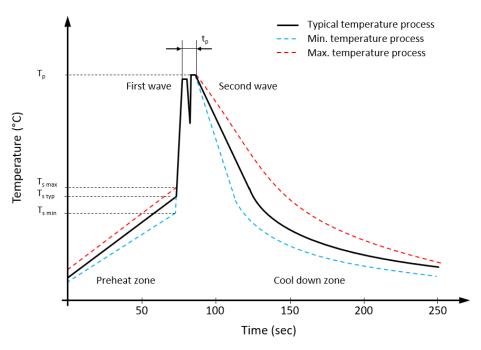


Coding list for "Day"





RECOMMENDED WAVE SOLDERING PROFILE A THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	T_{smin}	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T_{smax}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t _p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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